

**Surface Mount Superfast Recovery Rectifier**  
**Reverse Voltage – 50 to 600 V**  
**Forward Current –3 A**

**FEATURES**

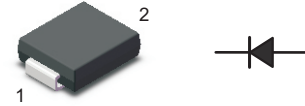
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

**MECHANICAL DATA**

- Case : SMC
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.22g / 0.0077oz

**PINNING**

- 1 Cathode
- 2 Anode



Top View  
 Marking Code: ES3A~ES3J  
 Simplified outline SMC and symbol

**Absolute Maximum Ratings and Characteristics**

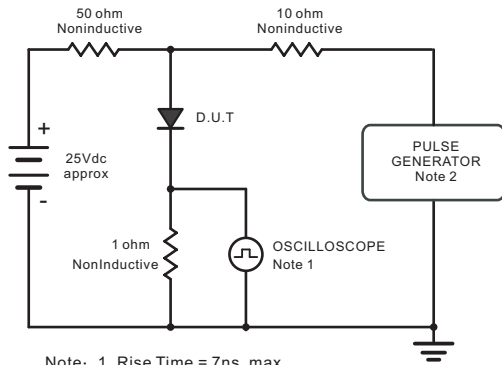
Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	ES3AC	ES3BC	ES3CC	ES3DC	ES3EC	ES3GC	ES3JC	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ }^\circ\text{C}$	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	90							A
Maximum Forward Voltage at 3 A	$V_F$	1				1.25		1.68	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 125\text{ }^\circ\text{C}$	$I_R$	5 100							$\mu\text{A}$
Typical Junction Capacitance at $V_R=4\text{V}$ , $f=1\text{MHz}$	$C_j$	40							pF
Maximum Reverse Recovery Time <sup>(1)</sup>	$t_{rr}$	35							ns
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$ $R_{\theta JC}$	40 16							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150							$^\circ\text{C}$

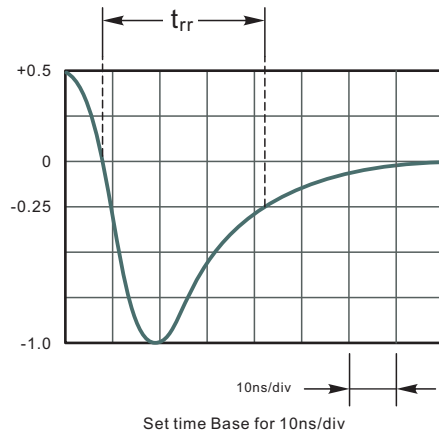
( 1 ) Measured with  $I_F = 0.5\text{ A}$ ,  $I_R = 1\text{ A}$ ,  $I_{rr} = 0.25\text{ A}$ .

( 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

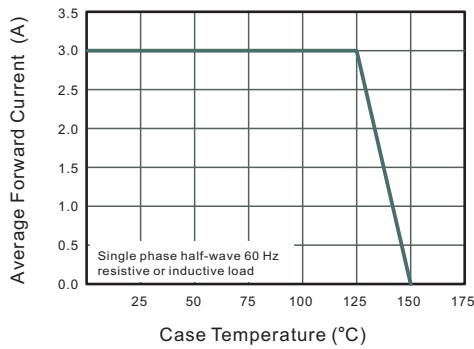
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**



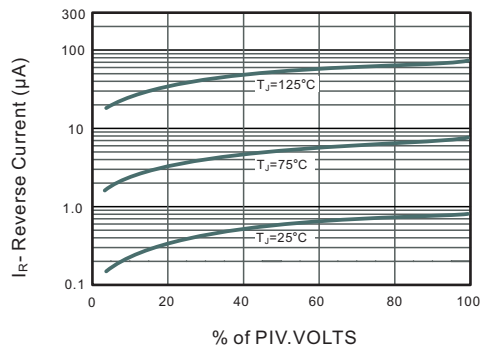
Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1megohm, 22pF.  
2. Rises Time = 10ns, max.  
Source Impedance = 50 ohms.



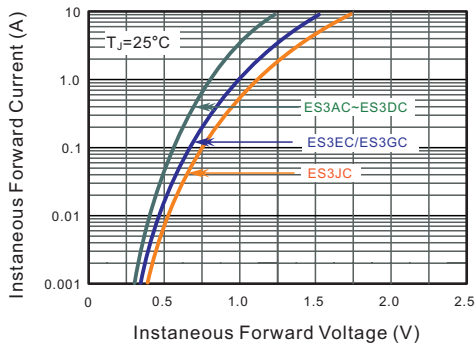
**Fig.2 Maximum Average Forward Current Rating**



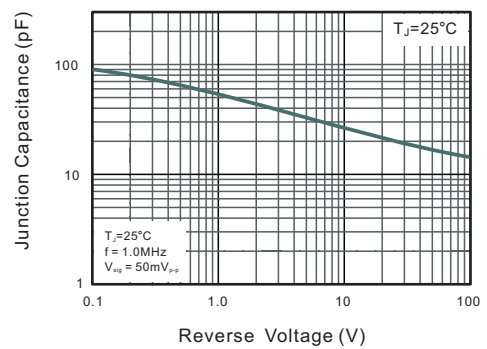
**Fig.3 Typical Reverse Characteristics**



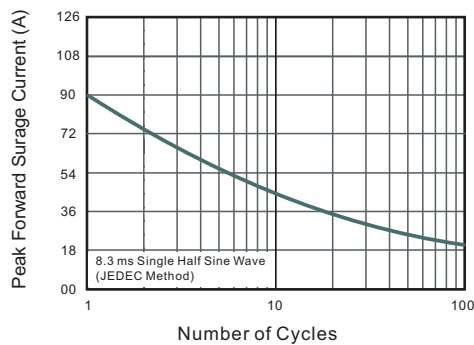
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**



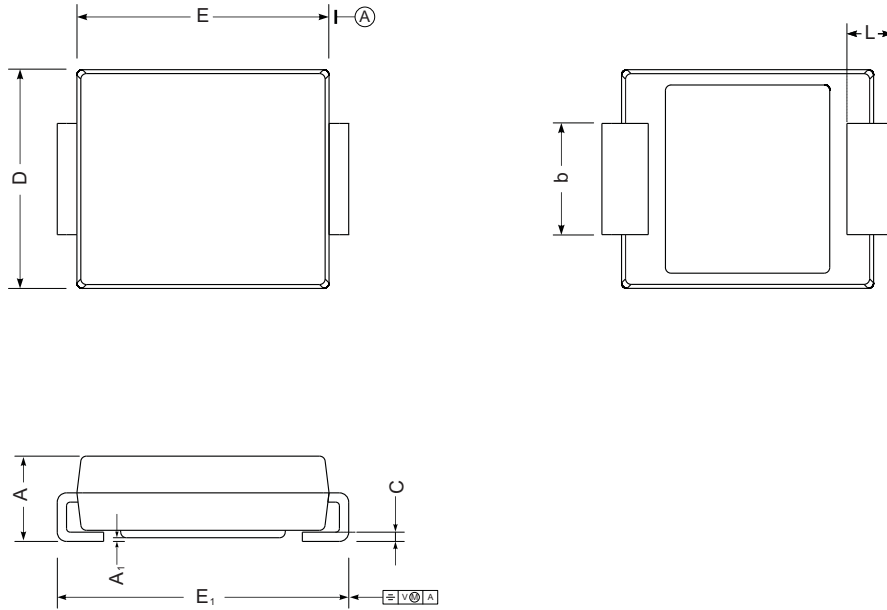
**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**



## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

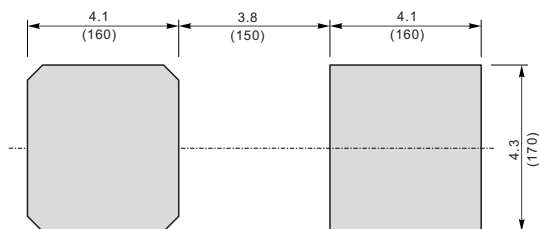
SMC



SMC mechanical data

UNIT		A	E	D	E <sub>1</sub>	A <sub>1</sub>	C	L	b
mm	max	2.62	7.0	6.2	8.0	0.21	0.31	1.6	3.25
	min	2.00	6.5	5.6	7.6	0.05	0.15	0.9	2.75
mil	max	103	276	244	315	8.3	12	63	128
	min	79	256	220	299	2.0	5.9	35	108

### The recommended mounting pad size



Unit:  $\frac{\text{mm}}{\text{mil}}$

### Marking

Type number	Marking code
ES3AC	ES3A
ES3BC	ES3B
ES3CC	ES3C
ES3DC	ES3D
ES3EC	ES3E
ES3GC	ES3G
ES3JC	ES3J